



A Novel Dynamic Avalanche Free Super-Junction Trench Clustered IGBT for High Power Applications Peng Luo¹, E. M. S. Narayanan¹, Shin-ichi Nishizawa², and Wataru Saito²

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DA during switch-off of TIGBTs

- DA can be triggered by:
- High current density
- High dV/dt
- Current filamentation
- DA poses a fundamental limit on:
- Operating current density
- Turn-off energy loss
- dV/dt controllability
- Therefore DA must be eliminated.

DA in Trench IGBT





- No electric field crowding in the TCIGBT.
- Trench gates are protected from peak electric field.

TCIGBT-High Current Density Operation







PMOS Actions in SJ-TCIGBT



(Source: P. Luo, et al, "Evaluation of Dynamic Avalanche Performance in 1.2kV MOS-Bipolar Devices," in IEEE Trans. on Electron Devices, Sep. 2020.)

- DA limits the reduction of Eoff in trench IGBTs.
- DA is enhanced at high current density operation.



(Source: P. Luo, et al, "Evaluation of Dynamic Avalanche Performance in 1.2kV MOS-Bipolar Devices," in IEEE Trans. on Electron Devices, Sep. 2020.)

Experiments confirm that **TCIGBTs** remain DA free even operated at 300A/cm².

Super-Junction TCIGBT





Hole current flowlines during turn-off

SJ-TCIGBT: High Power Density Operation



Comparison of Electric Field during turn-off

P-pillar

N-



Cross-section view of the SJ-TCIGBT

SJ structure can further enhance the PMOS effect in **TCIGBT**. Therefore, the **Eoff** can be further reduced.



Si SJ-TCIGBT

(J_=500A/cm²

Conclusions

- The DA limits the electrical performance of IGBT and SJ-IGBT.
- The SJ-TCIGBT remains DA free performance and low energy loss at Jc=500A/cm².
- Therefore, the SJ-TCIGBT device is well suited for high power applications.